



Material for Power Device and Electronic Components

Epoxy Underfills



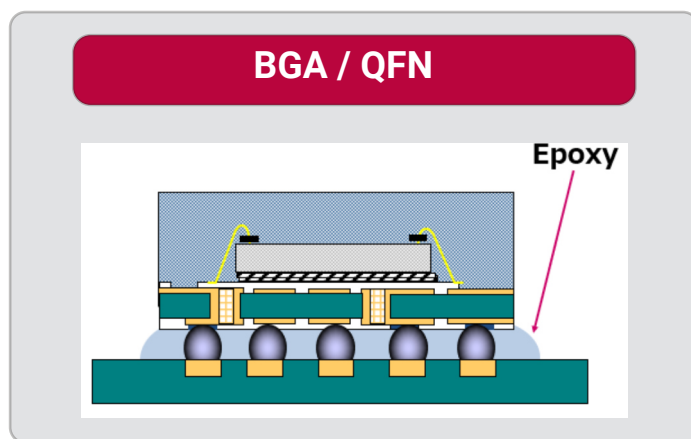
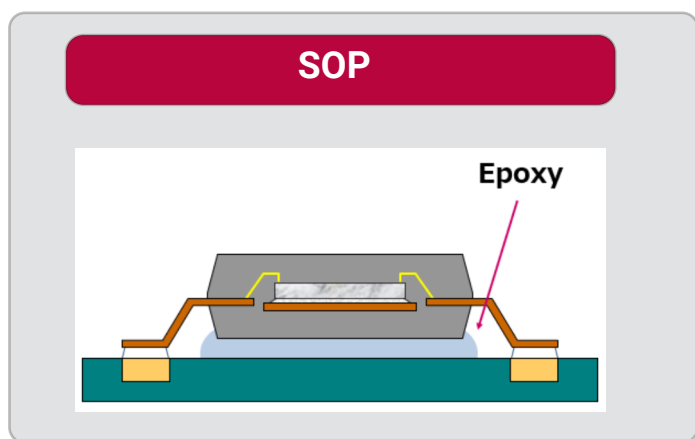
Solder Protection and Better Insulation

Underfill, DAM

Charateristics

- Easy handling for manufacturing
- Store at room temperature (pot life 7 days at 25 °C)
- No need to remove flux

Application for Automotive



	Condition	Unit	T-700/R-5901	R3501-01	R5011-X08
Application			Secondary UF	Secondary UF	DAM Corner Bond
Characteristic			Non SVHC Flux compatibility	Non SVHC Long shelf life	Non SVHC High reliability Low temperature cure
Curing Condition			150 °C / 1 h	160 °C / 40 min	120 °C / 1 h
Appearance			Black liquid	Black liquid	Black liquid
Viscosity	25 °C	Pa*s	7	25	290
Thixotropic Index	25 °C	-	-	-	3.5
CTE 1	≤ Tg	x10 ⁻⁶ /K	26	26	20
Tg (DMA)		°C	180	160	125 (TMA)
Modulus	25 °C	GPa	8	9	-

